



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D

*\* : Required Field*

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2016-03-23
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	IPD MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
<b>Legal Statement</b>	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
SM15T7V5AY	AHZH*TYUV75K	A	BOUSKOURA B/E	2016-03-23
Amount		UoM	Unit type	ST ECOPACK Grade
250.00		mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SOJ	6.69-5.63-2.38	2	J BEND	
Comment	SMC CLIP (SOD 15)			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	AHZH*TYUV75K					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	5.064	mg	supplier	die	Silicon (Si)	7440-21-3		4.910	mg	969583	19636
				supplier	metallization	Aluminium (Al)	7429-90-5		0.028	mg	5530	112
				supplier	metallization	Nickel (Ni)	7440-02-0		0.021	mg	4148	84
				supplier	metallization	Gold (Au)	7440-57-5		0.020	mg	3950	80
				supplier	Passivation	Silicon Oxide	7631-86-9		0.028	mg	5530	112
				supplier	back side metallization	Aluminium (Al)	7429-90-5		0.019	mg	3753	76
				supplier	back side metallization	Gold (Au)	7440-57-5		0.007	mg	1383	28
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.031	mg	6123	124
Leadframe	Copper & its alloys	79.541	mg	supplier	alloy	Copper (Cu)	7440-50-8		78.669	mg	989037	314676
				supplier	alloy	Iron (Fe)	7439-89-6		0.079	mg	993	316
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.024	mg	302	96
				supplier	metallization	Nickel (Ni)	7440-02-0		0.769	mg	9668	3076
Soft solder	Solder	4.445	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	4.156	mg	934983	16624
				supplier	solder	Tin (Sn)	7440-31-5		0.222	mg	49944	888
				supplier	solder	Silver (Ag)	7440-22-4		0.067	mg	15073	268
Encapsulation	Other Organic Materials	119.464	mg	supplier	mold compound	Silica, vitreous	60676-86-0		90.793	mg	760004	363172
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		12.185	mg	101997	48740
				supplier	mold compound	Phenol resin	9003-35-4		7.168	mg	60001	28672
				supplier	mold compound	Others	Proprietary		5.973	mg	49998	23892
				supplier	mold compound	Metal hydroxide	21645-51-2		2.389	mg	19998	9556
				supplier	mold compound	Carbon black	1333-86-4		0.956	mg	8002	3824
Connections coating	Solder	1.972	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.972	mg	1000000	7888
Clip	Copper & its alloys	39.514	mg	supplier	alloy	Copper ( Cu)	7440-50-8		39.514	mg	1000000	158056